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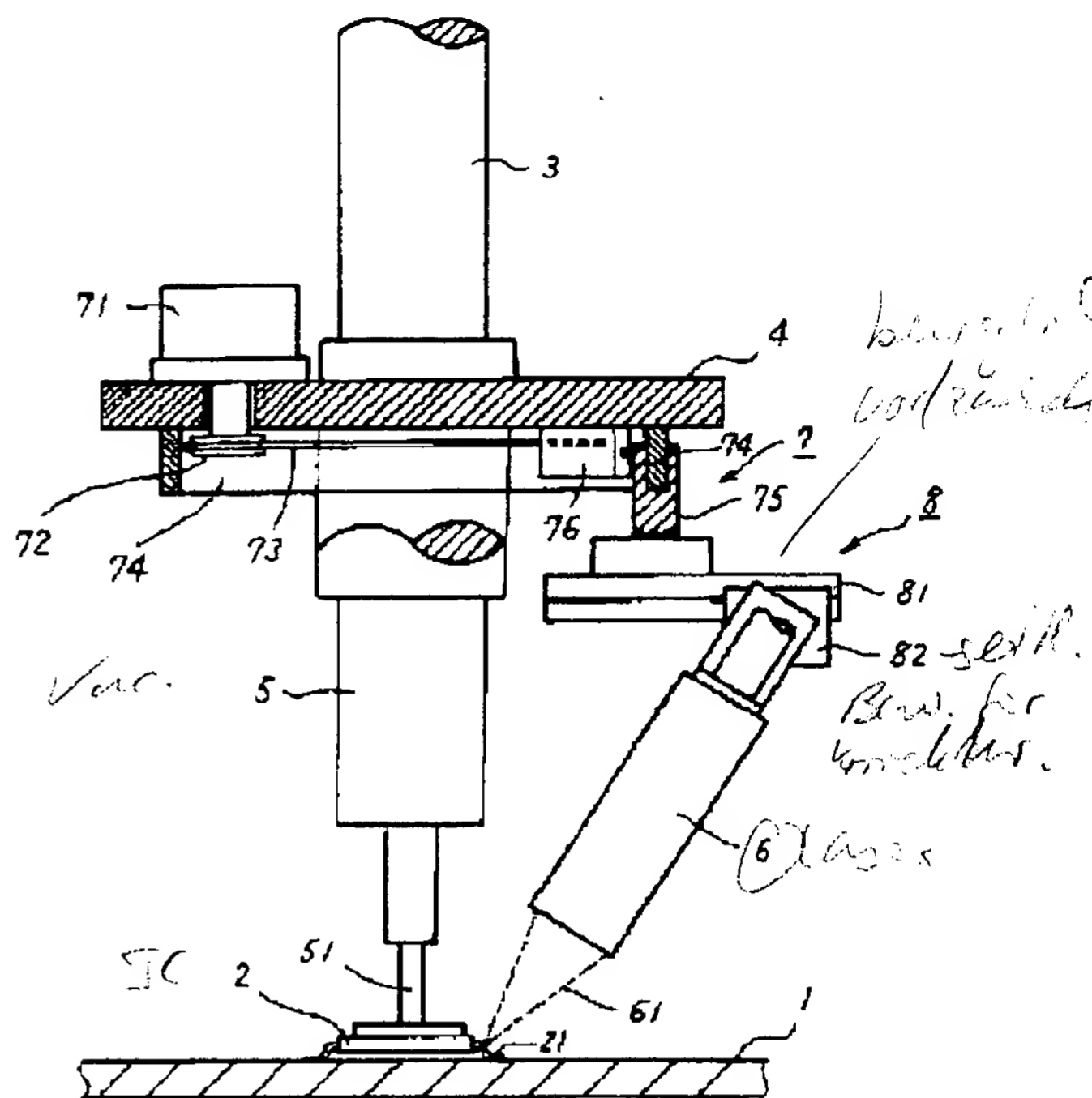
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TITLE : LASER SOLDERING DEVICE



ABSTRACT : PURPOSE: To perform the soldering of an IC package where a row of leads are projected at four sides with a simple mechanism by equipping this device with a driving mechanism which shifts the first slider along the first guide rail.

CONSTITUTION: An IC package 2 is sucked and held with a suction head 5, and this is installed in the mounting position of a printed wiring board 1, and also a supporting means 4 is positioned above the mounting position. In this condition, the first slider 75 is shifted along the first guide rail 74 by operating the drive mechanism of a peripheral mechanism 7. Accompanying this, a laser device 6 shifts the periphery of the IC package 2 and a laser beam is applied gradually to a row of leads 21 projected at four sides of the IC package 2. Moreover, in case that there is a discrepancy in the suction and retention position of the IC package by the suction head 5, the position of the laser beam is modified by shifting the second slider 82 of a reciprocating mechanism 8 in the longitudinal direction of the lead along the second guide rail 81.

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